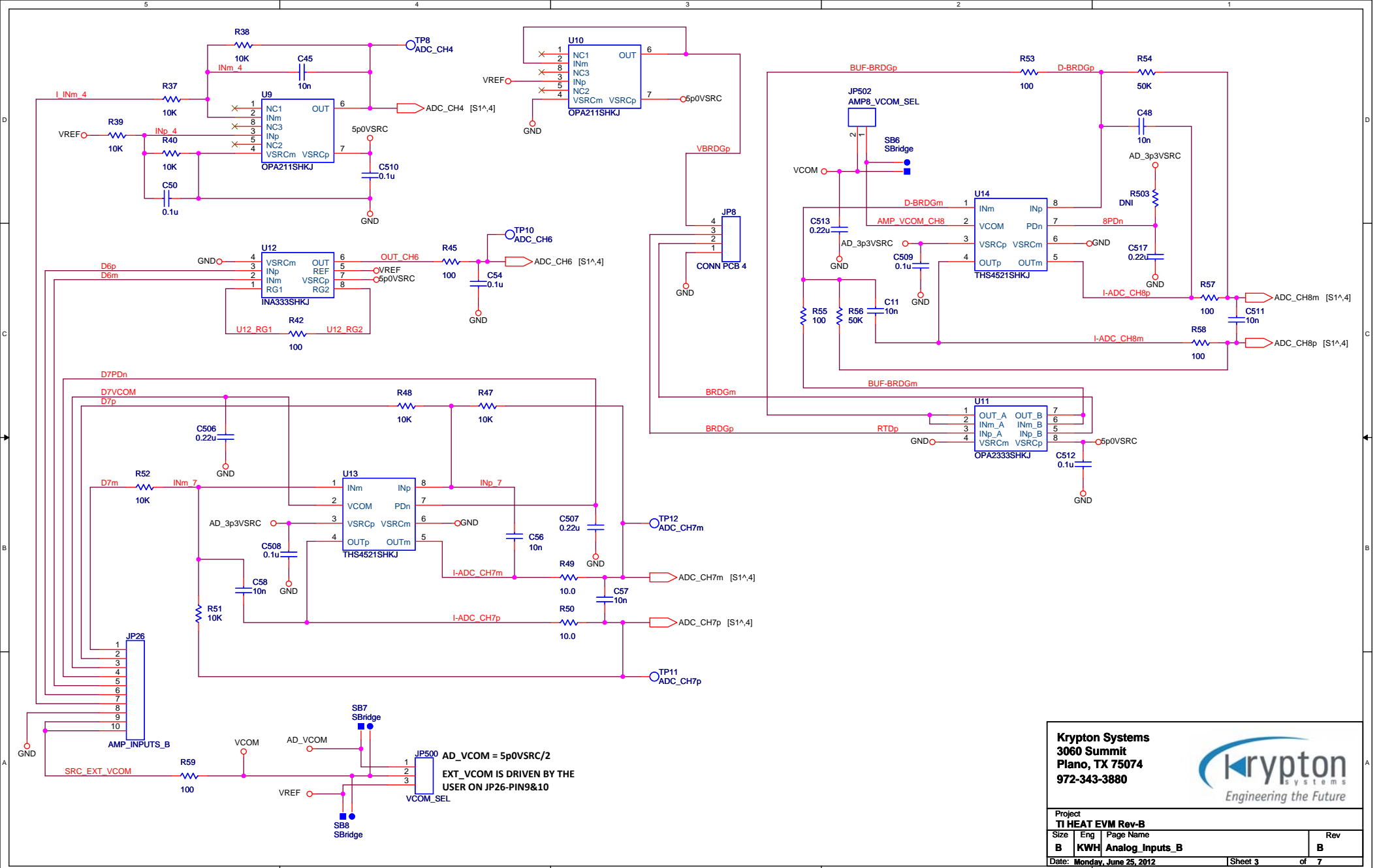


All capacitor values are shown as farads.
 All inductance values are shown as henries.
 All resistor values are shown as ohms.

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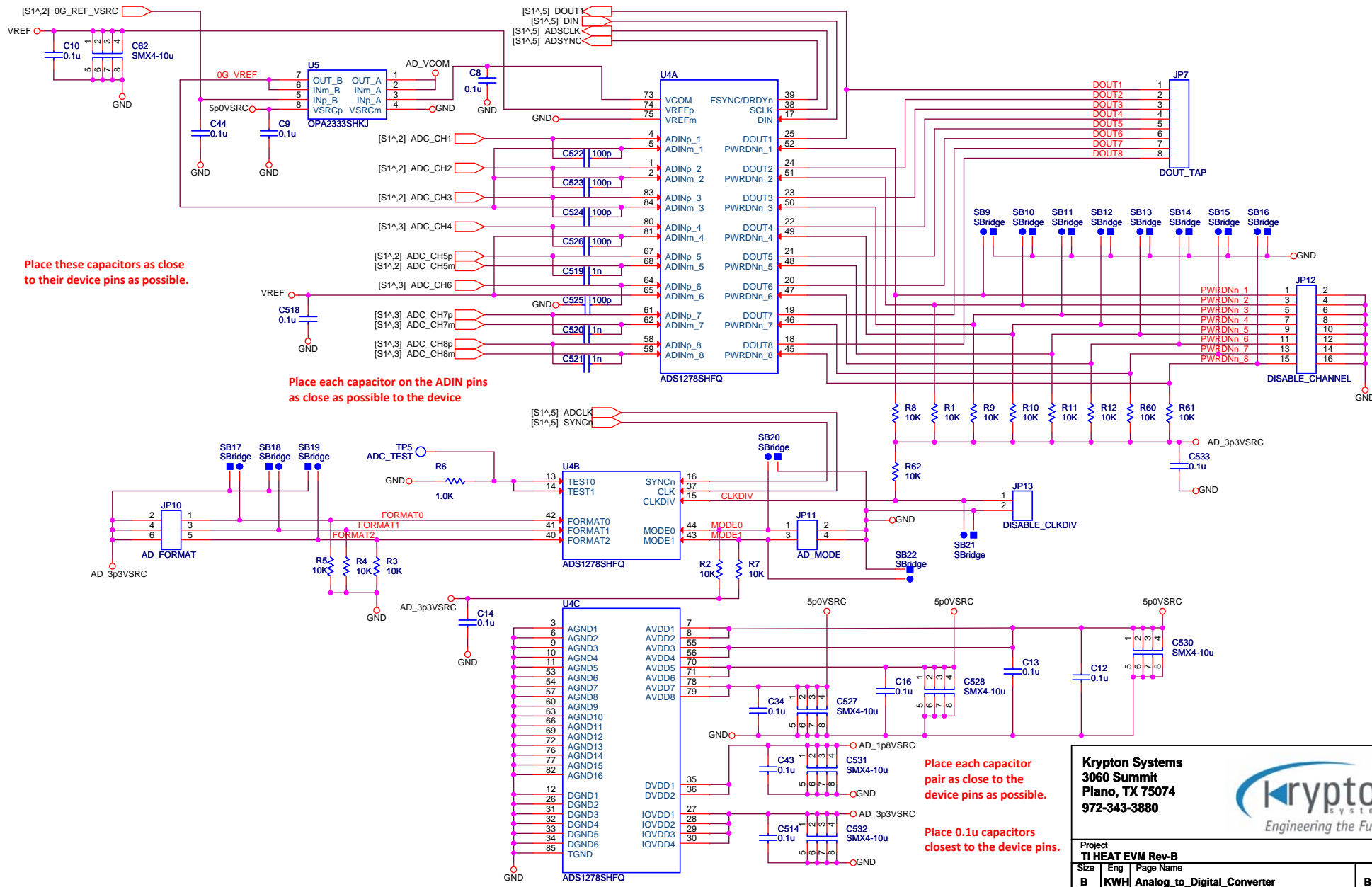


Project			
TI HEAT EVM Rev-B			
Size	Eng	Drawing File Name	Rev
A	KWH	Hierarchical_Block_Diagram	B
Date: Friday, May 18, 2012		Sheet 1	of 7



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Project			Rev
TI HEAT EVM Rev-B			B
Size	Eng	Page Name	
B	KWH	Analog_inputs_B	
Date: Monday, June 25, 2012			Sheet 3 of 7



Place these capacitors as close to their device pins as possible.

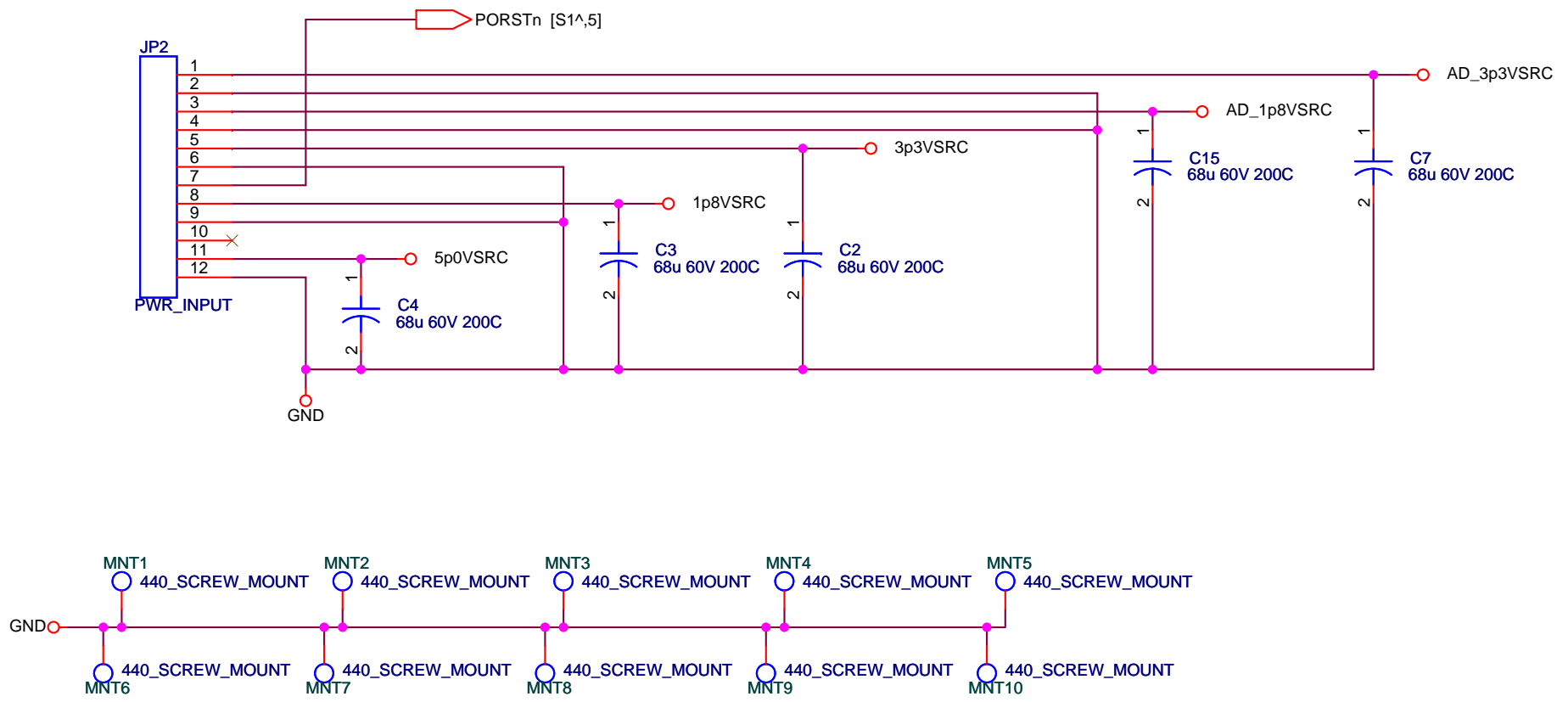
Place each capacitor on the ADIN pins as close as possible to the device

Place each capacitor pair as close to the device pins as possible.


Place 0.1u capacitors closest to the device pins.

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Project				Rev
TI HEAT EVM Rev-B				B
Size	Eng	Page Name		
B	KWH	Analog_to_Digital_Converter		
Date: Monday, June 25, 2012				Sheet 4 of 7



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Project
TI HEAT EVM Rev-B

Size	Eng	Page Name	Rev
A	KWH	Power_Input_and_Decoupling	B

Date: Friday, May 18, 2012 Sheet 6 of 7

TI_HEATEVM_REV-M_010312.DSN

FOLLOWING SCHEMATIC AND LAYER PLACEMENT REVIEW WE MODIFIED THE POWER INPUT STRUCTURES, CHANGED Y-AXIS AND Z-AXIS FILTERS SO THAT THEY EQUAL THE X-AXIS FILTERS. THE ITEMS IN REV-H, REV-J, AND REV-K WERE APPROVED.

BOARD WAS RELEASED TO LAYOUT. LAYOUT REVIEW WILL BE HELD WHEN PLACEMENT IS FINALIZED.

KWH 01/18/12

TI_HEATEVM_REV-N_010312.DSN

MODIFIED SCHEMATIC TO REFLECT THE ERRORS NOTED DURING LAYOUT

- 1) SB27 HAS AN OPEN PIN
- 2) SB7 AND SB8 ARE CONNECTED TO THE SAME NET. SB8 WAS MOVED TO CORRECT NET
- 3) BOARD GREW 0.4 INCH LONGER AND NEEDED TWO MORE MOUNTING HOLES
- 4) ADDED C535 AND C536 TO ARM7 SO THAT EACH SIDE OF THE DEVICE HAS A DECOUPLING CAP ON BOTH POWER NETS

KWH 01/23/12

TI_HEATEVM_REV-P_010312.DSN

ADDED FOOTPRINT TO JP2

KWH 01/23/12

TI_HEATEVM_REV-S_010312.DSN

THE REFHI NET WAS BROKEN, IT WAS CONNECTED AT R84.

KWH 01/27/12

TI_HEATEVM_REV-T_010312.DSN

SOME COMPONENT VALUES WERE UPDATED PER THE NEW DESIGN RULES FROM TI. SOME PART NUMBERS AND/OR FOOTPRINTS WERE UPDATED TO BRING BOM IN STEP WITH THE OLD BOM>

KWH 02/01/12

TI_HEATEVM_REV_A1_030912.DSN

REVIEW WITH HECTOR TORRES. SCHEMATIC EDITED BASED ON HECTORS FEEDBACK. A/D CONNECTIONS TO 0G NET, VCOM AND VREF NETS WERE MODIFIED

NIMA 03/09/12

**Krypton Systems
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Project			
TI HEAT EVM Rev-B			
Size	Eng	Page Name	Rev
A	KWH	ECN_and_Change Requests	B
Date: Friday, May 18, 2012			Sheet 7 of 7

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